



Title: METHOD OF USING TERNARY
COPPER ALLOY TO OBTAIN A LOW
RESISTANCE AND LARGE GRAIN SIZE
INTERCONNECT

Inventor(s): Lopatin et al.

Appl. No.: 09/994,395

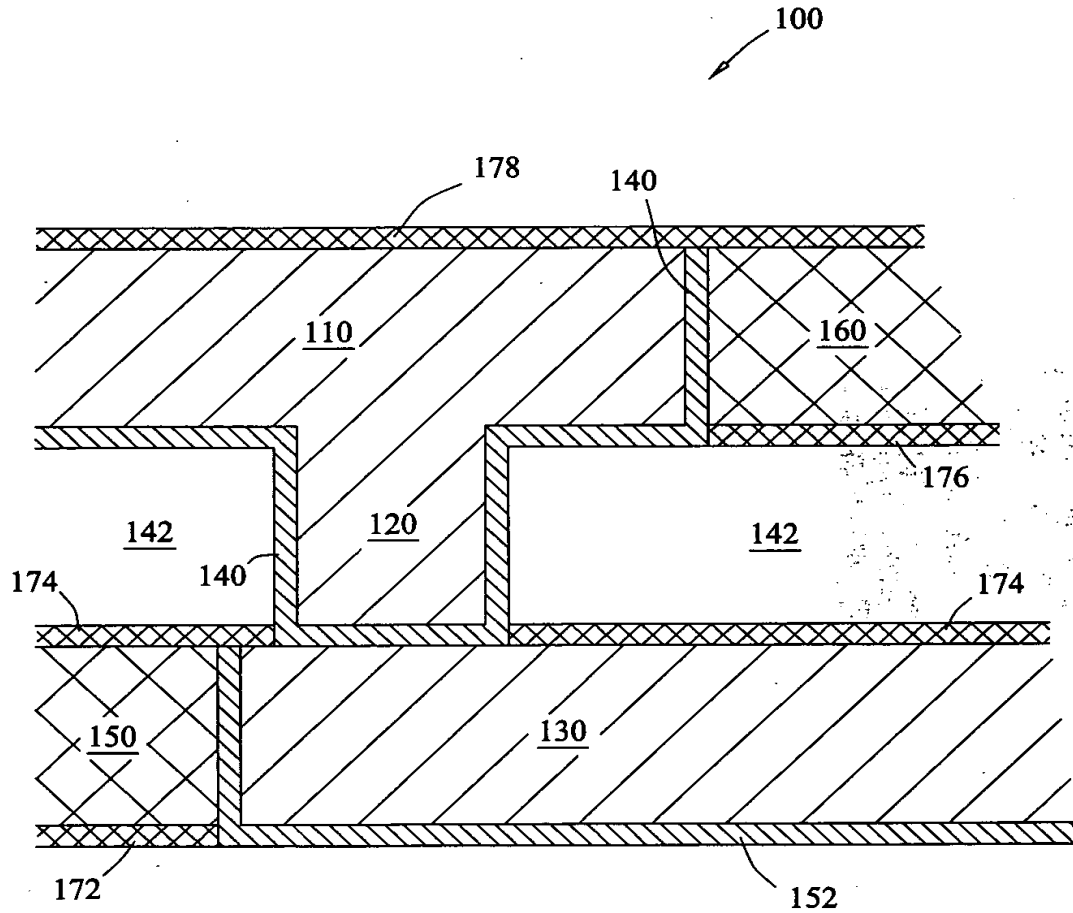


FIG. 1B
PRIOR ART

09994395-093002



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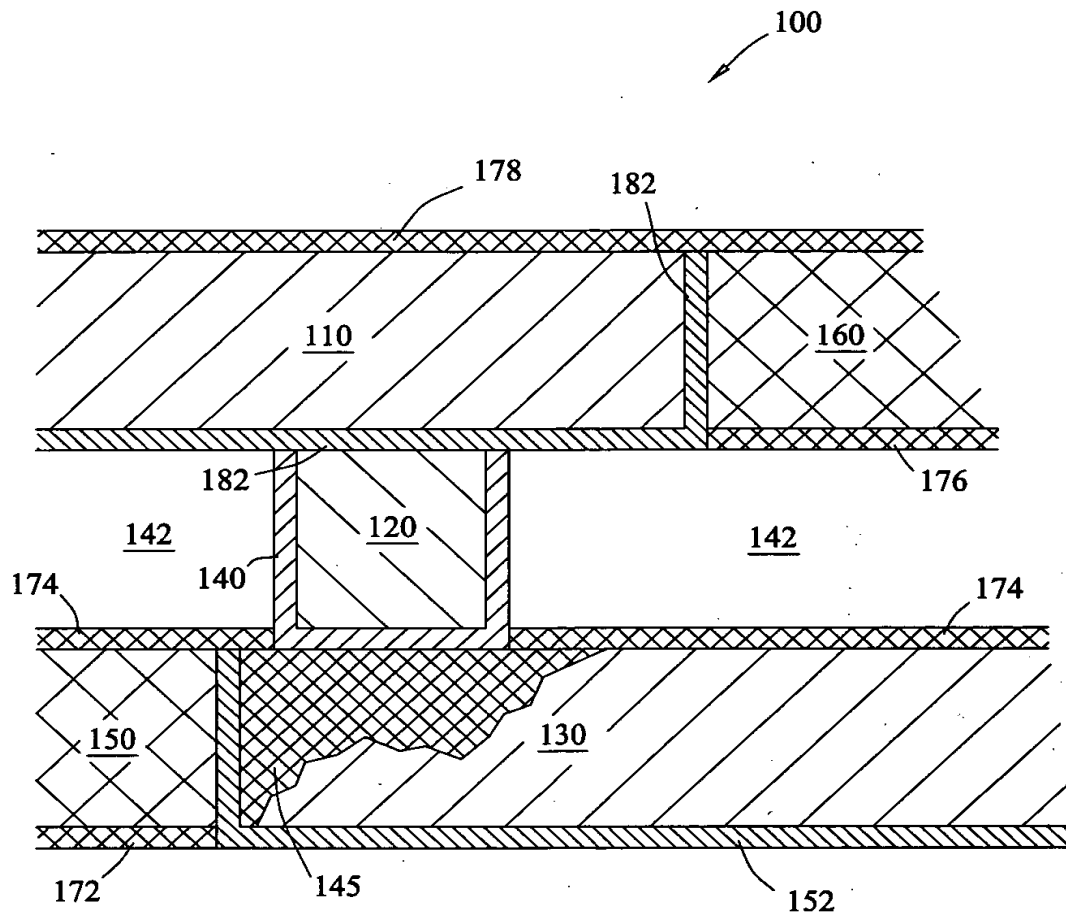


FIG. 2A
PRIOR ART

FIG. 2B
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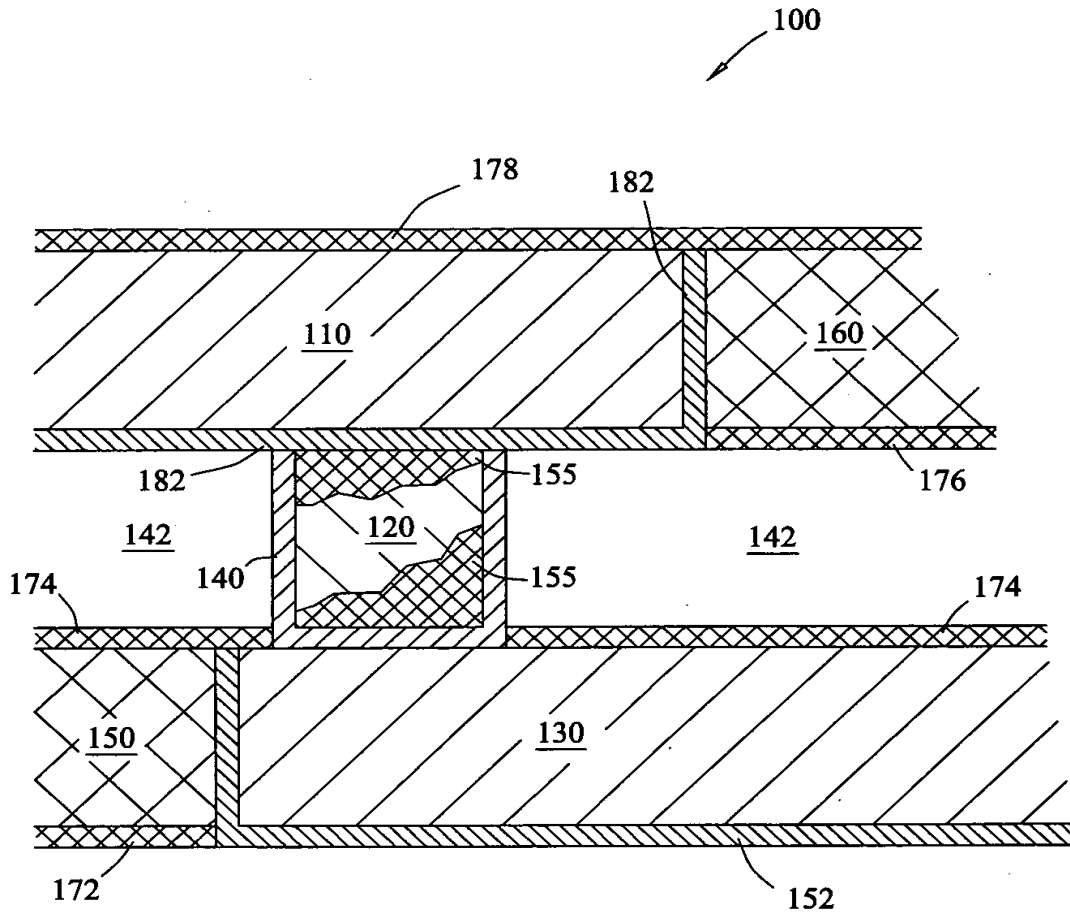


FIG. 3A
PRIOR ART

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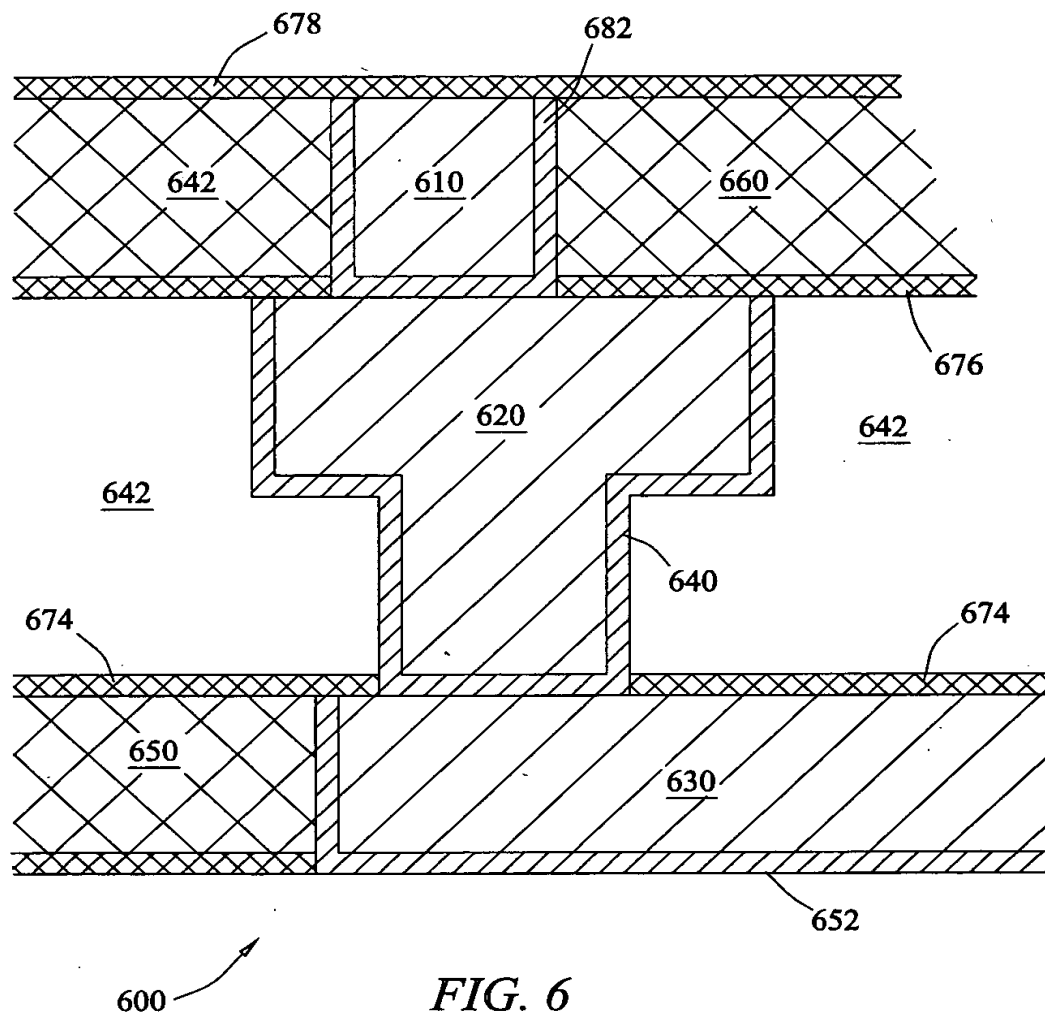
FIG. 3B
PRIOR ART



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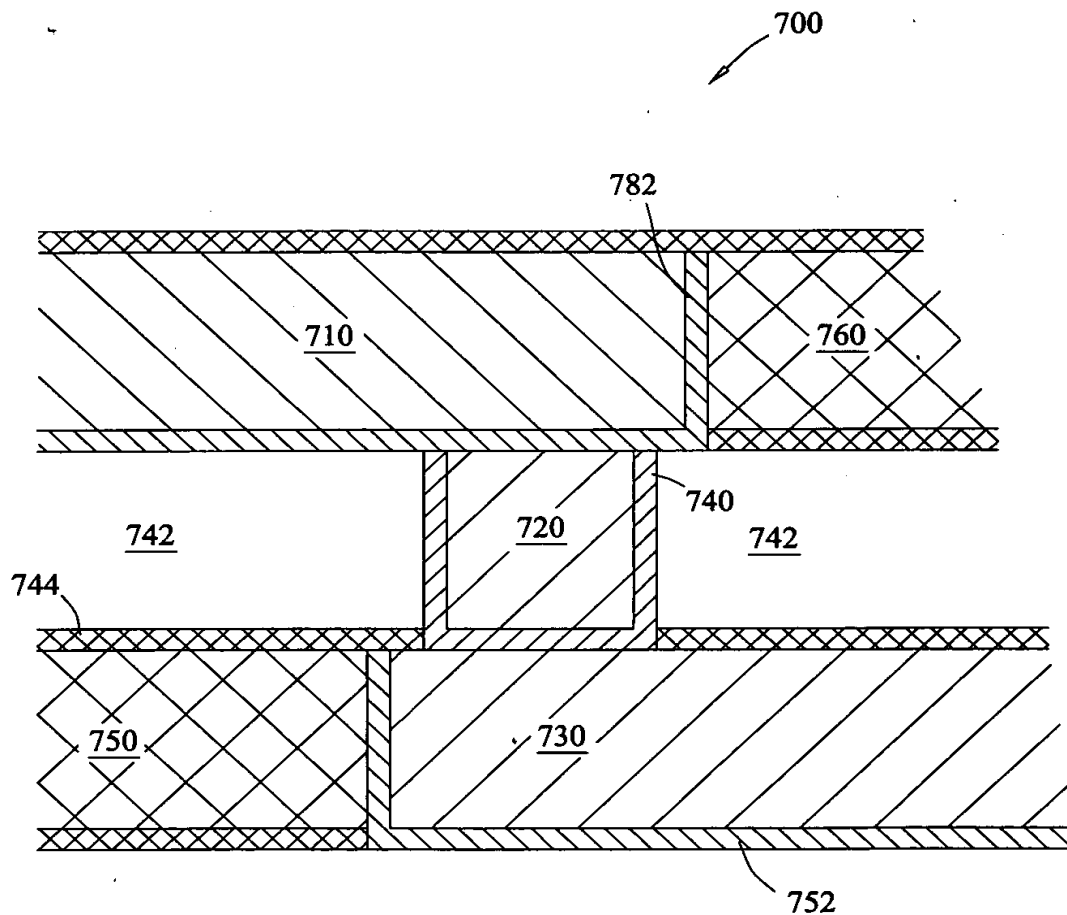


FIG. 7

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